

# CHO-BOND® 584-208

## TWO COMPONENT ELECTRICALLY CONDUCTIVE EPOXY ADHESIVE SYSTEM



### Customer Value Proposition:

CHO-BOND 584-208 is a two-component, silver filled conductive epoxy adhesive system designed for applications where a strong, highly conductive electrical bond must be achieved. CHO-BOND 584-208 is recommended for applications which require a conductive epoxy with an extended working life such as high volume part dispensing or complex part assembly operations.

Curing of CHO-BOND 584-208 can be achieved in as little as 45 minutes with heat to minimize equipment downtime and increase manufacturing throughput. With a 1:1 weight mix ratio, CHO-BOND 584-208 is easy to handle and use. Typical applications include bonding and grounding of electrical components, cold soldering, and bonding and sealing machined enclosures.



### Features and Benefits:

- Two component
- Silver filler
- Epoxy
- 1:1 Weight mix ratio
- Medium paste
- No VOCs
- Fast heat cure, increases throughput, minimizes equipment downtime.
- Good conductivity 0.002 ohm-cm
- 60 minute working life, works well over wide temperature range, good chemical resistance >1000 psi lap shear, good for permanently bonding surfaces.
- Easy to weigh out and mix.
- May be dispensed out of very small needles, fill small cracks and voids. Can be used on overhead or vertical surfaces
- Minimal shrinkage, no permits or ventilation required

